



Product Change Notification - JAON-30NOKK232

Date:

20 Nov 2018

Product Category:

8-bit Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

Affected CPNs:**Notification subject:**

CCB 3028.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN (6x6x0.9mm) package at NSEB assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN (6x6x0.9mm) package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB Assembly Site	NSEB Assembly Site
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

January 20, 2019 (date code: 1903)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.



Time Table Summary:

	November 2018					->	January 2019				
Workweek	44	45	46	47	48		01	02	03	04	05
Qual Report Availability			X								
Final PCN Issue Date			X								
Estimated Implementation Date									X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

PCN_JAON-30NOKK232_Qual_Report: Qualifies by similarity (QBS) selected products of the 0.25um TSMC wafer technology available in 28L QFN (6x6x0.9mm) using palladium coated copper with gold flash (CuPdAu) bond wire.

PCN_KSRA-11PKSB895_Qual_Report: Qualifies by similarity (QBS) selected products of the 0.25um TSMC wafer technology available in 28L QFN (6x6x0.9mm) based on a same package type, same package body size and same lead frame EFTEC-64T.

Revision History:

November 20, 2018: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-30NOKK232_Qual_Report.pdf](#)

[PCN_KSRA-11PKSB895_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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JAON-30NOKK232 - CCB 3028.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN (6x6x0.9mm) package at NSEB assembly site.

Affected Catalog Part Numbers(CPN)

DSPIC33FJ12GP202-E/ML	PIC18F27J13-I/ML	PIC24FJ32GA002-I/ML
DSPIC33FJ12GP202-I/ML	PIC18F27J13T-I/ML	PIC24FJ32GA002T-E/ML
DSPIC33FJ12GP202T-E/ML	PIC18F27J53-I/ML	PIC24FJ32GA002T-I/ML
DSPIC33FJ12GP202T-I/ML	PIC18F27J53T-I/ML	PIC24FJ32GA002T-I/ML030
DSPIC33FJ12MC202-E/ML	PIC18LF24J10-I/ML	PIC24FJ32GA002T-I/ML031
DSPIC33FJ12MC202-I/ML	PIC18LF24J11-I/ML	PIC24FJ32GA002T-I/MLC06
DSPIC33FJ12MC202T-E/ML	PIC18LF24J11T-I/ML	PIC24FJ32GA002T-I/MLC11
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DSPIC33FJ16GP102-E/ML	PIC18LF24J50T-I/ML	PIC24FJ32GA102-I/ML
DSPIC33FJ16GP102-H/ML	PIC18LF25J10-I/ML	PIC24FJ32GA102T-I/ML
DSPIC33FJ16GP102-I/ML	PIC18LF25J10T-I/ML	PIC24FJ32GB002-I/ML
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DSPIC33FJ16MC102-H/ML	PIC18LF25J50T-I/ML	PIC24FJ32MC102-I/ML
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PIC18F24J10-I/ML	PIC18LF26J50-I/ML	PIC24FJ48GA002T-I/MLB
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PIC18F25J50T-I/ML	PIC24FJ16GA002T-I/ML	PIC24HJ12GP202-I/ML
PIC18F26J11-I/ML	PIC24FJ16GA002T-I/ML023	
PIC18F26J11T-I/ML	PIC24FJ16GA002T-I/MLC06	
PIC18F26J13-I/ML	PIC24FJ16MC102-E/ML	
PIC18F26J13T-I/ML	PIC24FJ16MC102-H/ML	
PIC18F26J50-I/ML	PIC24FJ16MC102-I/ML	
PIC18F26J50T-I/ML	PIC24FJ16MC102T-E/ML	
PIC18F26J53-I/ML	PIC24FJ16MC102T-I/ML	
PIC18F26J53T-I/ML	PIC24FJ32GA002-E/ML	